

PRODUCT SPECIFICATION **FOR LCD MODULE**

Revision: 1.0

Model No: LSC397I04-MP-V2

Module Type: COG+FPC+B/L+CTP

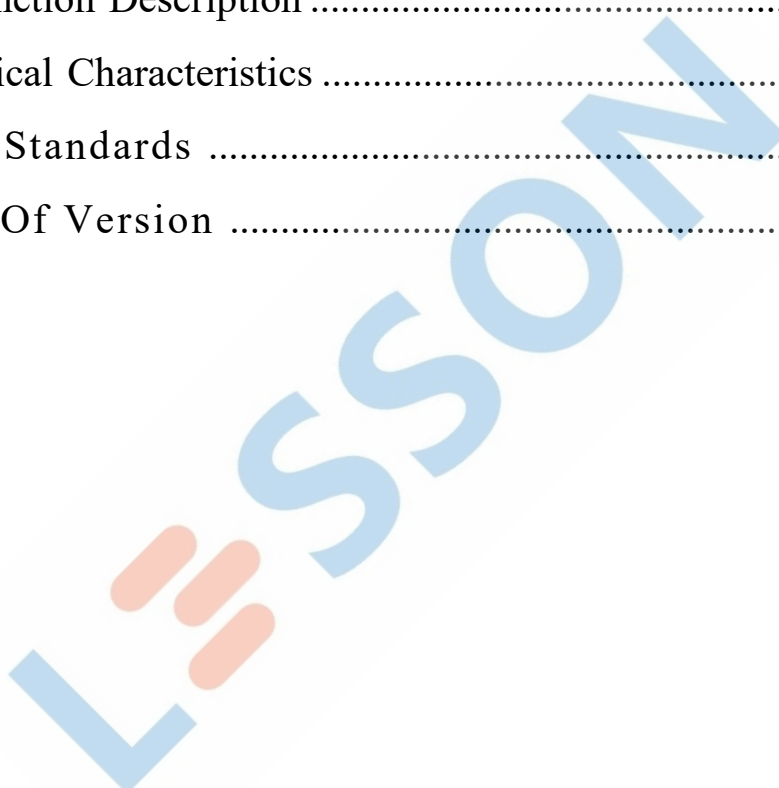
APPROVED SIGNATURE

- Approved Product Specification only
- Approved Product Specification and Samples

<u>Prepared By</u>	<u>Checked By</u>	<u>Approved By</u>

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1. General Description

LSC397I04-MP-V2 is a transmissive type a-Si TFT-LCD (amorphous silicon thin film transistor liquid crystal display) module, which is composed of a TFT-LCD panel, a driver circuit and a backlight unit. The panel size is 3.97 inch and the resolution is 480(RGB)*800, the panel can display up to 16.7 M colors.

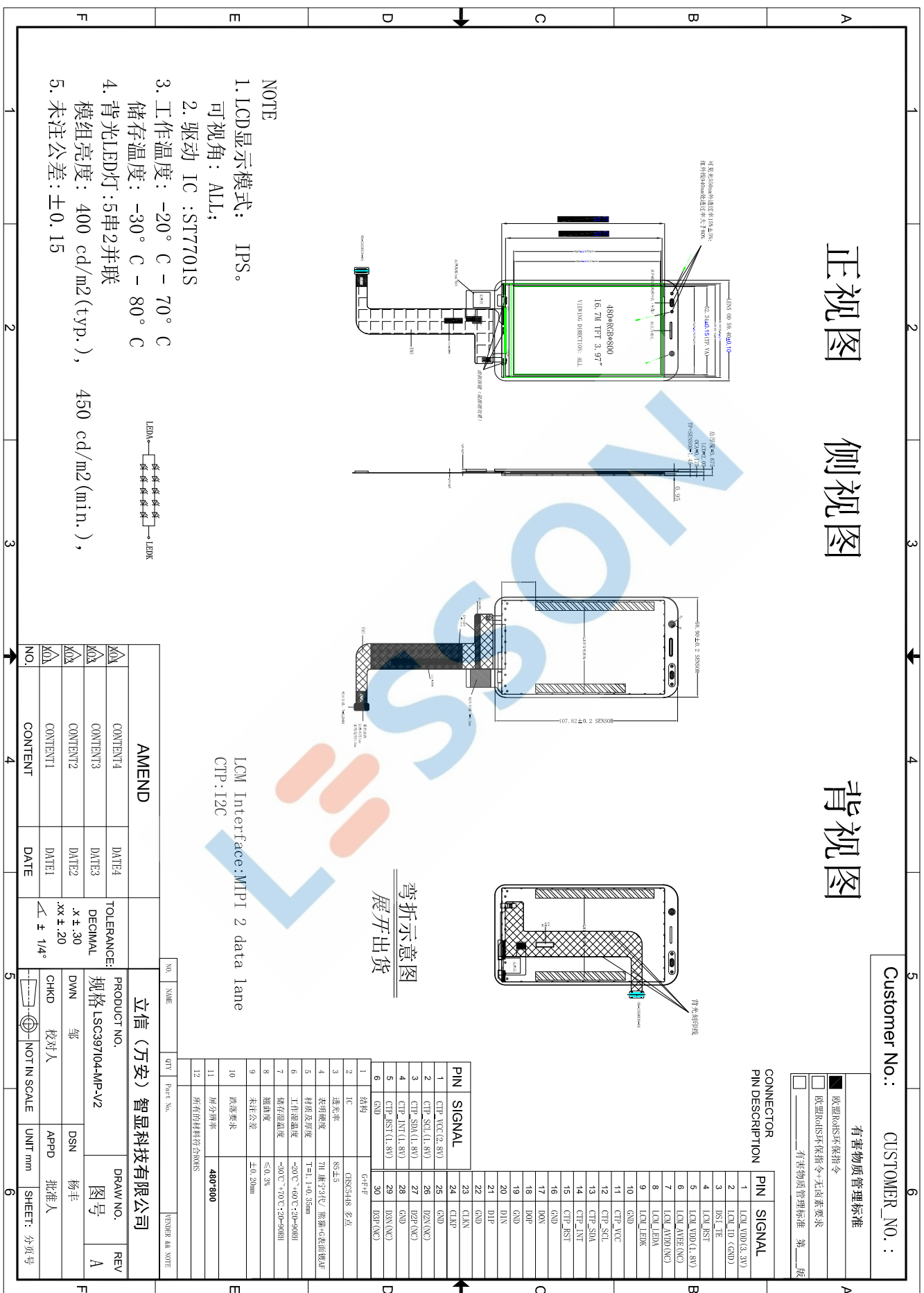
2. Physical Features

Display Mode	TFT-LCD Module
	Active matrix TFT, Transmissive type
Display Format	Graphic 480(RGB)×800 Dot-matrix
Input Data	MIPI input
Viewing Direction (Grayscale Inversion)	Free (IPS)
Drive	ST7701SN

3. Mechanical Specification

Item	Specification	Unit
Module size (H×V×D)	59.4 ×108.319 ×3.675	mm
Number of dots	480(RGB) × 800	pixel
Active area (H×V)	51.84×86.4	mm

4. Outline Dimension



5. Absolute Maximum Ratings

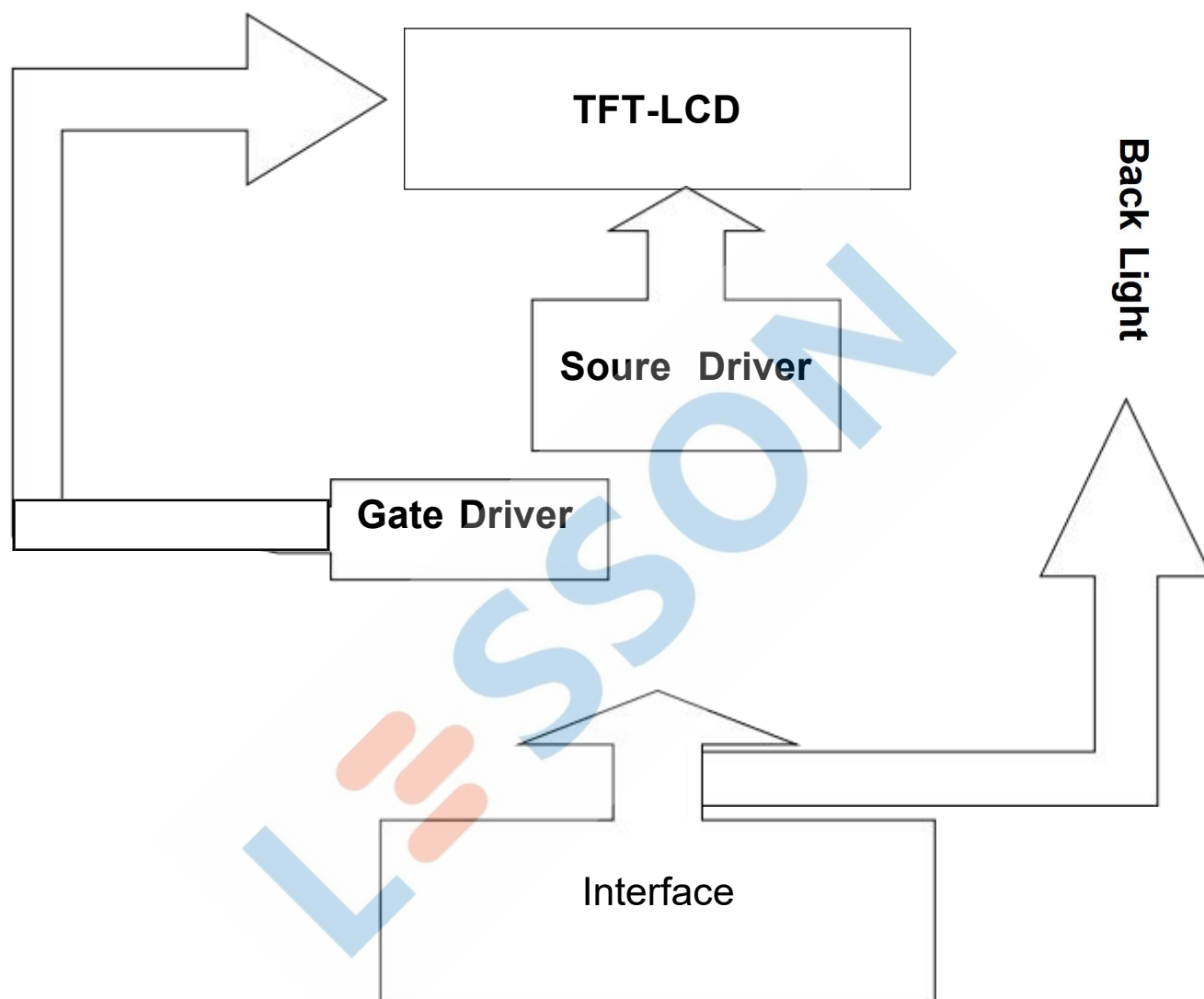
Item	Symbol	Min	Max	Unit	Remark
Supply voltage	VCC	-0.3	3.6	V	Note1 Note2
Supply voltage	IOVCC	-0.3	3.6	V	
Operating temperature	TOPR	-20	70	°C	
Storage temperature	TSTR	-30	80	°C	

6. Electrical Characteristics

Item		Symbol	Rating			Unit	Remark
			Min	Typ	Max		
Supply voltage		VCC	2.5	2.8	3.6	V	Note1
Supply voltage		IOVCC	1.65	1.8	3.3	V	
Input Voltage	L level	VIL	VSS	---	0.3*IOVCC	V	
	H level	VIH	0.7*IOVCC	---	IOVCC	V	
LCD Drive Power current		ILCD		TBD		mA	

7. Module Function Description

7- 1. Block Diagram Of LCM



7-2. Pin Description

PIN NO.	Symbol	I/O	Description
1	VDD(3.3V)	P	power supply
2	GND	P	Ground
3	TE	O	For IC Test. Leave the pin open when not in use.
4	RST	I	The external reset input
5	IOVCC(1.8V)	P	power supply
6	NC		
7	NC		
8	LEDA	P	Power for LED backlight anode
9	LEDK	P	Power for LED backlight cathode
10	GND	P	Ground
11	CTP_VCC(2.8V)	P	power supply
12	CTP_SCL(1.8V)	I	Serial clock pin
13	CTP_SDA(1.8V)	I	Serial data input/output bidirection pin
14	CTP_INT(1.8V)	I	Interrupt signal
15	CTP_RST(1.8V)	I	Reset signal pin
16	GND	P	Ground
17	D0N	I	MIPI DSI differential data pair
18	D0P	I	MIPI DSI differential data pair
19	GND	P	Ground
20	D1N	I	MIPI DSI differential data pair
21	D1P	I	MIPI DSI differential data pair
22	GND	P	Ground
23	CLKN	I	MIPI DSI differential clock pair
24	CLKP	I	MIPI DSI differential clock pair
25	GND	P	Ground
26	NC		
27	NC		
28	GND	P	Ground
29	NC		
30	NC		

7-3 Timing Characteristics

7.4.1.High Speed Mode

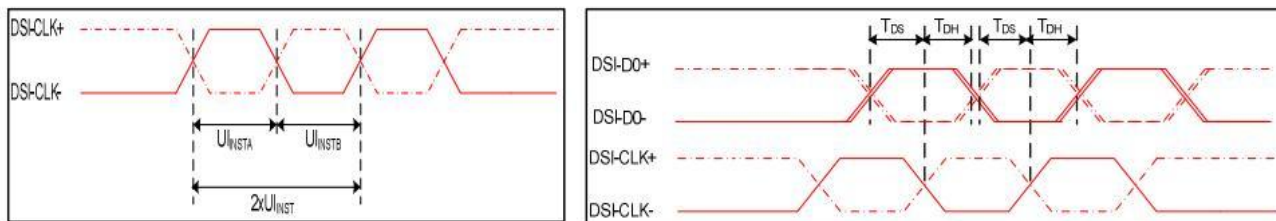


Figure 4 DSI clock channel timing

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
DSI-CLK+/-	$2 \times UI_{INSTA}$	Double UI instantaneous	4	25	ns	
DSI-CLK+/-	UI_{INSTA} UI_{INSTB}	UI instantaneous halves	2	12.5	ns	$UI = UI_{INSTA} = UI_{INSTB}$
DSI-Dn+/-	t _{DS}	Data to clock setup time	0.15	-	UI	
DSI-Dn+/-	t _{DH}	Data to clock hold time	0.15	-	UI	

Table 7 Mipi Interface- High Speed Mode Timing Characteristics

7.4.2.Lowe Power Mode

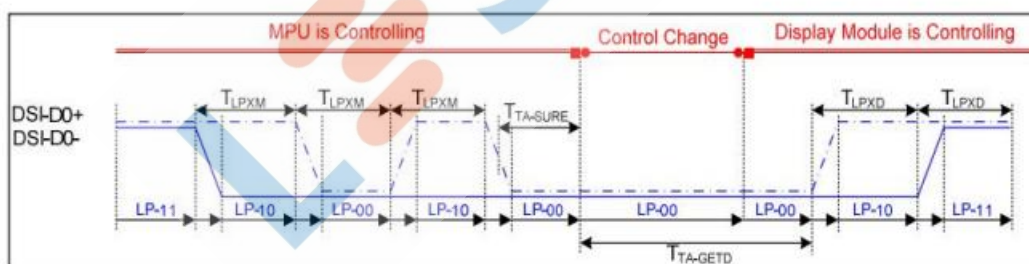


Figure 6 Bus Turnaround (BTA) from display module to MPU Timing

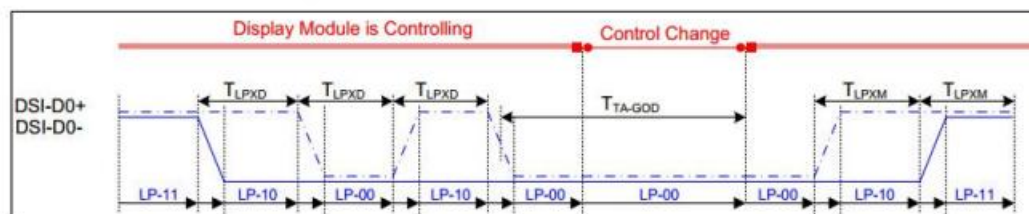


Figure 7 Bus Turnaround (BTA) from MPU to display module Timing

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
DSI-D0+/-	TLPXM	Length of LP-00,LP-01, LP-10 or LP-11 periods MPU→Display Module	50	75	ns	Input
DSI-D0+/-	TLPXD	Length of LP-00,LP-01, LP-10 or LP-11 periods MPU→Display Module	50	75	ns	Output
DSI-D0+/-	TTA-SURED	Time-out before the MPU start driving	T_{LPXD}	$2 \times T_{LPXD}$	ns	Output
DSI-D0+/-	TTA-GETD	Time to drive LP-00 by display module	$5 \times T_{LPXD}$		ns	Input
DSI-D0+/-	TTA-GOD	Time to drive LP-00 after turnaround request-MPU	$4 \times T_{LPXD}$		ns	Output

Table 8 Mipi Interface Low Power Mode Timing Characteristics

7.4.3.Reset Timing

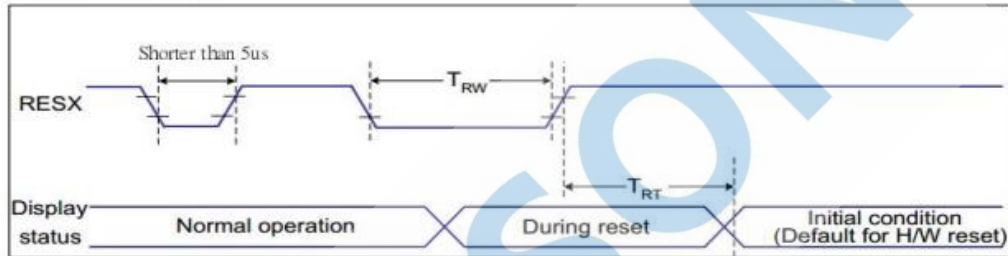


Figure 9 Reset Timing

$VDDI=1.8, VDD=2.8, AGND=DGND=0V, T_a=25^{\circ}C$

Related Pins	Symbol	Parameter	MIN	MAX	Unit
RESX	TRW	Reset pulse duration	10	-	us
	TRT	Reset cancel	-	5 (Note 1, 5) 120 (Note 1, 6, 7)	ms

Table 9 Reset Timing

8. Electro-Optical Characteristics

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Remark
Response time	Tr +Tf	$\theta_x = \theta_y = 0$	---	35	---	ms	Note 1
Contrast Ratio	CR		550	800	---	---	Note 2
Transmittance	T%		3.34	3.93	---	%	
Color Chromaticity (CIE1931)	White	W x	$\theta_x = \theta_y = 0$	0.292	---	---	
		W y		0.333	---	---	
Viewing angle	θ_T	CR > 10	---	85	---	Deg.	Note 3
	θ_B		---	85	---		
	θ_L		---	85	---		
	θ_R		---	85	---		
Luminance ($I_F = 40mA$)	L		400	450	---	cd/m ²	Note4

Note:

1. Viewing angle is the angle at which the contrast ratio is greater than 10. The viewing angles are determined for the horizontal or 3, 9 o'clock direction and the vertical or 6, 12 o'clock direction with respect to the optical axis which is normal to the LCD surface (see FIGURE 1).
2. Contrast measurements shall be made at viewing angle of $\Theta = 0$ and at the center of the LCD surface. Luminance shall be measured with all pixels in the view field set first to white, then to the dark (black) state. (see FIGURE 1) Luminance Contrast Ratio (CR) is defined mathematically.

$$CR = \frac{\text{Luminance when displaying a white raster}}{\text{Luminance when displaying a black raster}}$$

3. Transmittance is the Value with Polarizer
4. The color chromaticity coordinates specified in Table 5 shall be calculated from the spectral data measured with all pixels first in red, green, blue and white. Measurements shall be made at the center of the panel.
5. The electro-optical response time measurements shall be made as FIGURE 3 by switching the "data" input signal ON and OFF. The times needed for the luminance to change from 10% to 90% is Tr, and 90% to 10% is Td.

Figure 1. The Definition of V_{th} & V_{sat}

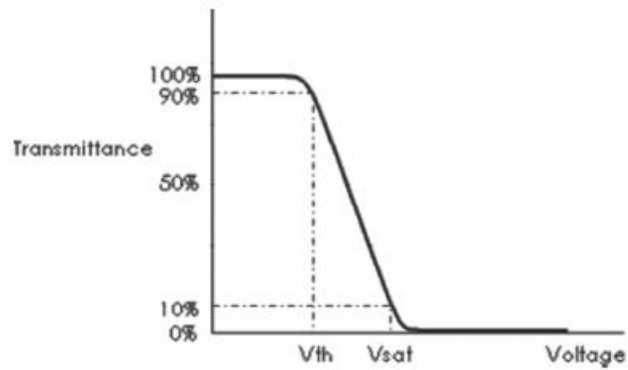


Figure 2. Measurement Set Up

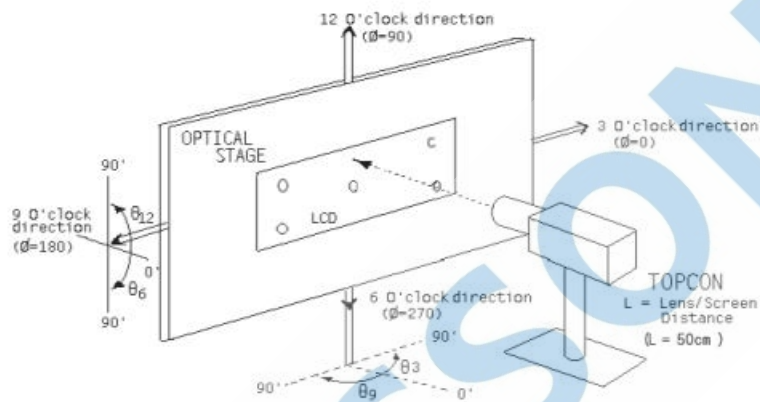
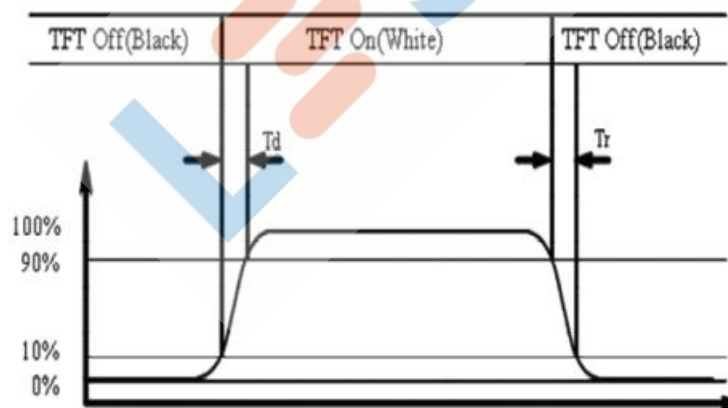
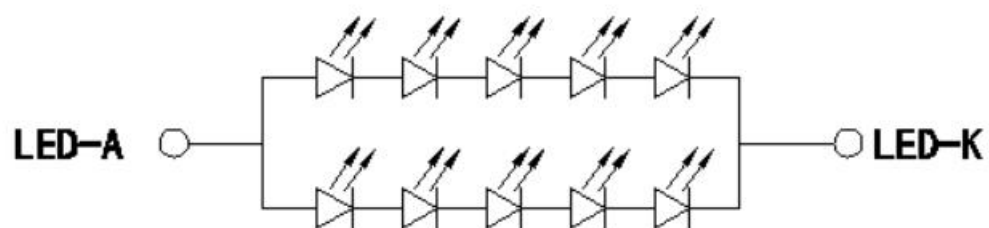


Figure 3. Response Time Testing



Note(4) Backlight circuit



$I_f=40\text{mA}$ $V_f=14\text{V}\sim 16\text{V}$

9. Inspection Standards

1. AQL(Acceptable Quality Level)

AQL of major and minor defect

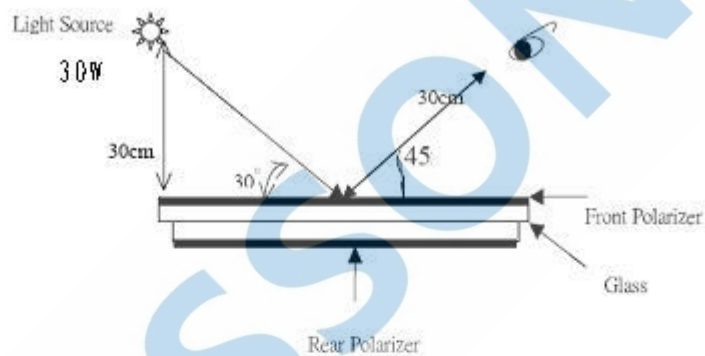
According to GB/T 2828-2003 ; , normal inspection, Class II

MAJOR DEFECT	MINOR DEFECT
0.65	1.5

2. Basic conditions for inspection

The LCM face to us, in normal environment, About an angle of incidence 30, a distance of 30cm with normal eye, with an angle of 45 degree to check the products without uncovering the film!

(As shown below)

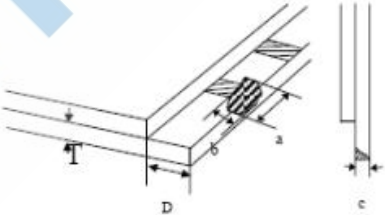
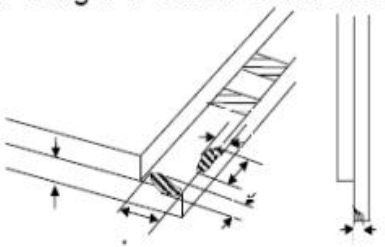


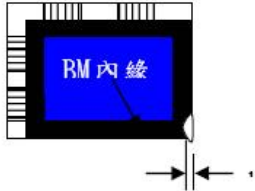
3. Inspection item and criteria

3.1 Visual inspection criterion in immobility

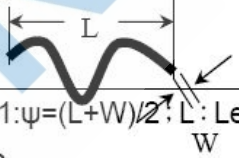
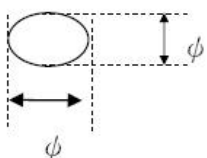
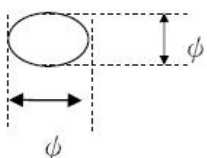
3.1.1 Glass defect

No	Defect item	Criteria	Remark
1	Dimension Unconformity (Major defect)	By Engineering Drawing	

No	Defect item	Criteria	Remark
2	Cracks (Major defect)	1.Linear cracks on panel 【Reject】 2. Nonlinear crack contrast by limited sample	
3	Glass extrude the conductive area (minor defect)	a: disregards and no influence assemblage 1) $b \leq 1/3$ Pin width(non bonding area) 【Accept】 2) bonding area $\leq 0.5\text{mm}$ 【Accept】	a:Length, b:Width
4	Pin-side , conductive area damaged (minor defect)	(a c : disregards) $b \leq 1/3$ of effective length for bonding electrode 【Accept】	a:Length·b:Width·c:Thickness 
5	Pin-side , non-conductive area damaged (minor defect)	1) Damage area don't touch the ITO (Inclueing contraposition mark,except scribing mark) 【Accept】 2) $c < T$ $b \leq \text{BM } 1/3$ of width 【Accept】 3) $c = T$ b not touch the seal glue 【Accept】 4) a disregards	a:Length·b:Width·c:Thickness 

No	Defect item	Criteria	Remark
6	Non-pin-side damage (minor defect)	$c < T$ 1) b exceeds 1/3 BM $c = T$ b not touch the seal glue 【Reject】 【Reject】	c : Thickness b: width of damage 

3.1.2 LCD appearance defect (View area)

No	Defect item	Criteria		Remark
1	Fiber 、glass cratch 、polarizer scratch/folded (minor defect)	Specification	Allowable	note1: L : Length , W : Width note2: disregard if out of AA 
		$0.05\text{mm} < W \leq 0.1\text{mm};$ $L \leq 3.0\text{mm}$	1	
		$W > 0.1\text{mm}; L > 3.0\text{mm}$	0	
2	Polarizer bubble 、 concave and convex (minor defect)	$\psi \leq 0.2\text{mm}$	disregard	note 1: $\psi = (L+W)/2$; L : Length , W : Width note2: disregard if out of AA 
		$0.2\text{mm} < \psi \leq 0.3\text{mm}$	2	
		$0.3\text{mm} < \psi \leq 0.5\text{mm}$	1	
		$0.5\text{mm} < \psi$	0	
3	Black dots 、dirty dots 、 impurities 、eyewinker (Major defect)	$\psi \leq 0.15\text{mm}$	disregard	note2: disregard if out of AA 
		$0.15\text{mm} < \psi \leq 0.25\text{mm}$	2	
		$0.25\text{mm} < \psi \leq 0.3\text{mm}$	1	
		$0.3\text{mm} < \psi$	0	
4	Polarizer prick (Major defect)	$\psi \leq 0.1\text{mm}$	disregard	note1: $\psi = (L+W)/2$; L= Length , W=Width note2: the distance between two dots > 5mm
		$0.1\text{mm} < \psi \leq 0.25\text{mm}$	3	
		$\psi > 0.25\text{mm}$	0	

3.1.3 .FPC

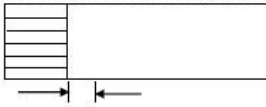
No	Defect item	Criteria		Remark
1	Copper screen peel (Major defect)	Copper screen peel 【 Reject】		
2	No release tape or peel (Major defect)	No release tape or peel 【 Reject】		
3	Dirty dot and impurity of FPC for customer using side (minor defect)	Specification	Allowable	note1: Cannot have stride ITO impurities
		$\psi \leq 0.25\text{mm}$	2	
		$\psi > 0.25$	0	

3.1.4 Black tape & Mara tape

1	FPC or H/S black tape shift (minor defect)	1.shift spec: 1)glue to the polarize 【 Reject】 2) IC bare 【 Reject】 2. left-and-right spec: 1) exceed of FPC edge or H-S edge 【 Reject】 2)IC bare 【 Reject】	
2	No black tape (Major defect)	No black tape 【 Reject】	
3	Tape position mistake (minor defect)	Not by engineering drawing 【 Reject】	
4	Mara tape defect (minor defect)	Peel before pulling the protecting film. 【 Reject】	

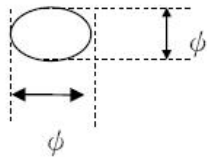
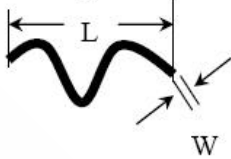
3.1.5 Silicon and Tuffy glue

No	Defect item	Criteria	Remark
1	Quantity of silicon (minor defect)	Uncover the ITO and circuit area. 【 Reject】	note: compared by engineering drawing.

No	Defect item	Criteria	Remark
2	Tuffy glue (minor defect)	1. Uncover the reveal copper area 【 Reject】 2. Cover layer 0.3mm(Min) ~ 3.0mm(Max) 【 accept】	note:if customer has special requirement , refer to the technical document. 
3	Depth of glue covering (minor defect)	Depth of glue covering overtop front Polarizer 【 Reject】	Except of the special requirement °

3.2 Electrical criteria

No	Defect item	Criteria	Remark
1	No display (Major defect)	No display 【 Reject】	
2	Missing line (Major defect)	Missing line 【 Reject】	
3	Seg-com light and dark (Major defect)	Seg-com light and dark 【 Reject】	ND filter 2% test
4	No display in immobility (Major defect)	No display in immobility 【 Reject】	
5	Flicker of Pattern (Major defect)	Flicker of Pattern 【 Reject】	
6	Mura (Major defect)	ND filter 2% test	
7	Over current (Major defect)	Over current 【 Reject】	
8	Voltage out of specification (Major defect)	Voltage out of specification 【 Reject】	
9	Pattern blur ,error code (Major defect)	Pattern blur ,error code 【 Reject】	
10	Dark light, Flicker (Major defect)	Dark light, Flicker 【 Reject】	

No	Defect item	Criteria	Remark	
11	Black/White dots 、 Dirty dots 、 eyewinker (Major defect)	Specification	Allowable	Note1: disregard if out of AA 
		$\psi \leq 0.15\text{mm}$	disregard	
		$0.15\text{mm} < \psi \leq 0.25\text{mm}$	2	
		$0.25\text{mm} < \psi \leq 0.3\text{mm}$	1	
		$0.3\text{mm} < \psi$	0	
12	Fiber 、 glass cratch 、 polarizer scratch/folded (minor defect)	$W \leq 0.03\text{mm}$	disregard	note1: L : Length 、 W : Width note2: disregard if out of AA 
		$0.03\text{mm} < W \leq 0.05\text{mm} ;$ $L \leq 3.0\text{mm}$	2	
		$0.05\text{mm} < W \leq 0.1\text{mm} ;$ $L \leq 3.0\text{mm}$	1	
		$W > 0.1\text{mm} ; L > 3.0\text{mm}$	0	

10.Records Of Version

Version	Revise Date	Page	Content
00	2024-7-20	all	New released

LESSON